*Appendix No.2*

**Institute of Solid State Physics, University of Latvia**

**Auction commission**

*Ķengaraga Street 8, Riga, LV-1063*

*personal data*

*(name, surname, personal identification code, address of the declared place of residence)*

*OR*

*details of the legal entity*

*(name, registration number and registered office)*

*Phone, e-mail*

**APPLICATION FOR PARTICIPATION IN THE AUCTION**

I would like to participate in the auction of the intellectual property- technology with European patent application “A MICROFLUIDIC DEVICE FOR SIMULATING ORGAN FUNCTIONS”, which is patent pending (European patent application No.21215336.5) and the total amount of our / my proposed fixed payments is \_\_\_\_\_\_\_\_\_\_ EUR (amount in words) (excluding VAT), which consists of payments in accordance with the terms of the draft contract attached to the auction regulations.

I certify that I am aware of the risks of the technology patenting process, and as a result of unsuccessful patent registration, I will not make any claims against the auctioneer.

I confirm that I have read and agree to the terms and conditions of the auction and the conditions included in the draft agreement on the sale / transfer of intellectual property, which are understandable and acceptable to me.

I confirm that there are no obstacles for participation in the auction.

|  |  |  |  |
| --- | --- | --- | --- |
|  |  |  |  |
| date |  |  | Name, Surname, signature, title |